



## Final Product Change Notification

202308015F01 : UTL as Additional Assembly and Test Facility for Smart Power Products

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Oct 06, 2023 **Effective date:** Jan 04, 2024

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### Management summary

Adding UTL as additional assembly and test facility for Smart Power products to create more sourcing reliability, flexibility and capacity expansion.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

Adding UTL as additional assembly and test facility for Smart Power products to create more sourcing reliability, flexibility and capacity expansion.

### Reason

Create more sourcing flexibility and capacity expansion.

### Identification of Affected Products

Top Side Marking

UTL products can be identified at marking line C: second character: "R".

## Product Availability

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### Sample Information

Samples are available upon request

### Production

Planned first shipment Jan 05, 2024

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Products will be delivered from multiple assembly/test fabs.

## Additional information

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Self qualification: [view online](#)

Additional documents: [view online](#)

## Timing and Logistics

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 05, 2023.

## Remarks

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## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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